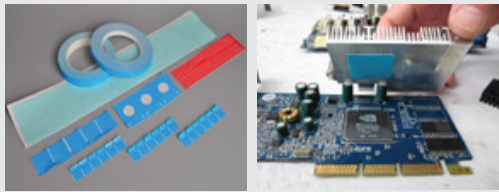


Technical Data Sheet

EverTherm thermal tape is widely used in bonding heat sinks to microprocessors and power consuming semiconductors. It features a high adhesive strength and low thermal impedance, which can effectively replace silicone grease and mechanical fixation.



Material Properties

- High-strength viscosity suitable for various surfaces
- Double-sided pressure-sensitive adhesive tape
- High thermal conductive acrylic adhesive
- Can withstand long-term high temperature working environment

Applications

- ✓ LED lighting products
- ✓ Chassis, frame or other cooling components
- ✓ Large capacity drive
- ✓ Heat pipe assembly
- ✓ RDRAM memory
- ✓ High frequency micro processing chip
- ✓ Notebook and desktop computers



EVSA408FG

Color	White	Visual
Substrate	Acrylic resin (Acrylic)	***
Substrate reinforcement	Fiberglass	***
Thickness(mm)	0.20±0.01	ASTM D374
Dielectric Breakdown Voltage@AC	>4000V	ASTM D149
Release force	1.8kg/25mm	PSTC-3
Shear strength1.0 kg loading on 25 mm x 25 mm	> 48 hrs	PSTC-7
Heat resistance0.5kg loading on25mm x 25mm at 80	> 24 hrs	***
Thermal conductivity (W/m.k)	1.0	ASTM D5470
Operating temperature()	-30 ~ 130	***
RoHS	PASS	IEC 62321
Halogen	PASS °	EN14582
REACH	PASS	EN14372

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.